Title County Book				
L Number	Hits	Search Text	DB	Time stamp
1	34429	(insulative or insulating or insulator or	USPAT;	2003/11/13
		dielectric) with (polymer or organic)	US-PGPUB	11:12
2	968	((insulative or insulating or insulator	USPAT;	2003/11/13
		or dielectric) with (polymer or organic))	US-PGPUB	11:13
		same (monomer or oligomer)		
3	. 1	(((insulative or insulating or insulator	USPAT;	2003/11/13
		or dielectric) with (polymer or organic))	US-PGPUB	11:10
		same (monomer or oligomer)) and (aerosol		
4	2	with heating) (((insulative or insulating or insulator	HGDDM.	2002/11/12
4		or dielectric) with (polymer or organic))	USPAT; US-PGPUB	2003/11/13
		same (monomer or oligomer)) and (aerosol	US-PGPUB	11:12
	,	same heating)		
5	611	(((insulative or insulating or insulator	USPAT;	2003/11/13
		or dielectric) with (polymer or organic))	US-PGPUB	11:13
		same (monomer or oligomer)) and heating	05 10102	
6	12	((((insulative or insulating or insulator	USPAT;	2003/11/13
		or dielectric) with (polymer or organic))	US-PGPUB	11:13
		same (monomer or oligomer)) and heating)		
		and aerosol		
7	5	(((((insulative or insulating or	USPAT;	2003/11/13
		insulator or dielectric) with (polymer or	US-PGPUB	11:11
		organic)) same (monomer or oligomer)) and		
		heating) and aerosol) and @ad<20010420		/
8	4	((((((insulative or insulating or	USPAT;	2003/11/13
		insulator or dielectric) with (polymer or	US-PGPUB	11:11
		organic)) same (monomer or oligomer)) and heating) and aerosol) and @ad<20010420)		
		not ((((insulative or insulating or		1
		insulator or dielectric) with (polymer or		
		organic)) same (monomer or oligomer)) and		
		(aerosol same heating))		·
9	2	(((insulative or insulating or insulator	USPAT;	2003/11/13
		or dielectric) with (polymer or organic))	US-PGPUB	11:12
		same (monomer or oligomer)) and (aerosol		
]		same heating)		
10	24769	(insulative or insulating or insulator or	EPO; JPO;	2003/11/13
		dielectric) with (polymer or organic)	DERWENT;	11:13
			IBM_TDB	0000/11/25
11	1004	((insulative or insulating or insulator	EPO; JPO;	2003/11/13
		or dielectric) with (polymer or organic)) same (monomer or oligomer)	DERWENT;	11:13
12	64	same (monomer or oligomer) (((insulative or insulating or insulator	IBM_TDB EPO; JPO;	2003/11/13
12		or dielectric) with (polymer or organic))	DERWENT;	11:13
		same (monomer or oligomer)) and heating	IBM TDB	11.10
13	2	((((insulative or insulating or insulator	EPO; JPO;	2003/11/13
		or dielectric) with (polymer or organic))	DERWENT;	11:13
		same (monomer or oligomer)) and heating)	IBM TDB	
	L	and aerosol	_	

US-PAT-NO:

6387453

DOCUMENT-IDENTIFIER:

US 6387453 B1

TITLE:

Method for making

surfactant-templated thin films

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Brief Summary Text - BSTX (7): According to the present invention, an evaporation-induced self-assembly method is provided to prepare a porous, hybrid surfactant-templated, thin film by mixing a silica sol precursor, a solvent, a surfactant, and an interstitial compound to first form a silica sol, evaporating a portion of the solvent to form a liquid crystalline thin film mesophase and heating the liquid crystalline mesophase to remove surfactant. Because the surfactant is at a concentration less than the critical micelle concentration, evaporation of a portion of the solvent, such as can occur during coating onto a substrate or during aerosol processing or spray drying, forms a liquid-phase crystalline mesophase material. Coating onto a substrate by spin-coating, dip-coating and spray-coating forms a thin film wherein the thin film can be either ordered or disordered. Processing by aerosol processing or spray drying permits formation of structured particles.

Detailed Description Text - DETX (18):

In another embodiment, the interstitial compound can be a hydrophobic organic polymer, oligomer, or swelling agent that swells the liquid crystalline mesoporous material and thereby increases the porosity of the formed thin film.

Materials prepared with hydrophobic <u>organic</u> polymers were prepared with a resulting <u>dielectric</u> constant less than 2, showing potential use for applications requiring low-dielectric constant materials.